

Guest Editorial

Special Issue on Plenary, Invited, and Selected Minicourse Papers From ICOPS 2023

THE historic 50th Anniversary International Conference on Plasma Science (ICOPS) was held in Santa Fe, NM, USA, on May 21–25, 2023, with Edl Schamiloglu (The University of New Mexico, The Bronx, NY, USA) serving as the General Chair and Sal Portillo (The University of New Mexico) serving as the Technical Chair. The ICOPS meeting was an outstanding success, with more than 500 contributed abstracts from all over the world. Complementing the technical program was an all-star selection of invited talks, plenary talks, and mini-courses, which this Special Issue serves to highlight.

The Special Issue begins with a paper by Baryshev and Muehle [A1] from Michigan State University, East Lansing, MI, USA. Next is a paper by Moon et al. [A2] from Ulsan National Institute of Science and Technology, Ulsan, South Korea. This paper is followed by a paper by Dong et al. [A3] from the National Key Laboratory of Power Transmission Equipment Technology, Chongqing, China. The next paper by Klemmer et al. [A4] is a collaborative contribution between authors at the University of Nevada, Reno, NV, USA; Los Alamos National Laboratory, Santa Fe, NM; Zap Energy, Inc., Seattle, WA, USA; and the University of Washington, Seattle. This is followed by a paper by Tang et al. [A5] from the University of Washington. The final contribution is by Benford [A6] from Microwave Sciences, which appropriately caps off this Special Issue dedicated to the historic 50th Anniversary ICOPS.

These contributions represent a strong sample of the technical program of ICOPS 2023. The editors would like to thank the authors for their contributions and the reviewers for their considerable time and effort in reviewing these manuscripts. We would like to thank the organizers of the ICOPS conference for their coordination of strong technical contributions, including the invited and plenary talks, and the mini-course contributions. We wish to thank Steve Gitomer

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APPENDIX: RELATED ARTICLES

- [A1] S. V. Baryshev and M. Muehle, “Scalable production and supply chain of diamond wafers using microwave plasma: A mini-review,” *IEEE Trans. Plasma Sci.*, vol. 52, no. 4, pp. 1082–1103, Apr. 2024.
- [A2] S. Moon, D. Yu, and E. Choi, “High-power millimeter-wave orbital angular momentum mode identification using double slit interference,” *IEEE Trans. Plasma Sci.*, vol. 52, no. 4, pp. 1104–1109, Apr. 2024.
- [A3] S. Dong et al., “All-solid-state synergistic bipolar pulse generator for gene electrotransfer,” *IEEE Trans. Plasma Sci.*, vol. 52, no. 4, pp. 1110–1117, Apr. 2024.
- [A4] A. W. Klemmer et al., “Progress on multielement spectroscopic temperature and impurity studies on a high flow velocity Z-pinch,” *IEEE Trans. Plasma Sci.*, vol. 52, no. 4, pp. 1118–1128, Apr. 2024.
- [A5] A. Tang, A. Ong, N. Beck, J. S. Meschke, and I. Novosselov, “Surface virus inactivation by impinging flow nonthermal plasma reactor,” *IEEE Trans. Plasma Sci.*, vol. 52, no. 4, pp. 1129–1136, Apr. 2024.
- [A6] J. Benford, “History and future of high power microwaves,” *IEEE Trans. Plasma Sci.*, vol. 52, no. 4, pp. 1137–1144, Apr. 2024.